

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5595366

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
LIANG YI	06/25/2019
ZHIGUO LI	06/25/2019
CHI REN	06/25/2019
QIUJI ZHAO	06/25/2019
BOON KEAT TOH	06/25/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16455297
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)660-0809
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	949-660-0761
<b>Email:</b>	jcpatents@gmail.com
<b>Correspondent Name:</b>	J C PATENTS
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<b>ATTORNEY DOCKET NUMBER:</b>	JCLA89149
<b>NAME OF SUBMITTER:</b>	JIawei HUANG
<b>SIGNATURE:</b>	/JIawei HUANG/
<b>DATE SIGNED:</b>	06/27/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 7</b>	
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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**STRUCTURE OF MEMORY DEVICE**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

\_\_\_\_\_ Filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

**WHEREAS,** 1. United Microelectronics Corp.  
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

UMCD-2019-0102  
89149-US-PA

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yi Liang Date: JUN 25 2019

Legal Name of Sole or First Inventor: **Liang Yi**

Residence: Singapore, Singapore

Mailing Address: BLK9A Woodlands Drive72 #11-18, Singapore 738093

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Li Zhiguo Date: JUN 25 2019

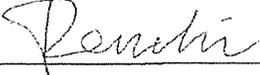
Legal Name of Additional Joint Inventor, if any: Zhiguo LI

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Mailing Address: 06-202 BLK690E Woodslan Dr. 75, Singapore

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DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature:  Date: JUN 25 2019

Legal Name of Additional Joint Inventor, if any: Chi Ren

Residence: Singapore, Singapore

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DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Zhao Qiuji Date: JUN 25 2019

Legal Name of Additional Joint Inventor, if any: Qiuji Zhao

Residence: Singapore, Singapore

Mailing Address: BLK75, #05-29, PASIR RIS GROVE, SINGAPORE, 518207

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DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Toh Boon Keat Date: JUN 25 2019

Legal Name of Additional Joint Inventor, if any: **Boon Keat Toh**

Residence: Singapore, Singapore

Mailing Address: Blk 662D Edgedale Plains #04-704, Singapore 824662